

September 2010
UniFET-II TM

FDP7N60NZ / FDPF7N60NZ N-Channel MOSFET 600V, 6.5A, 1.25 Ω

Features

- $R_{DS(on)} = 1.05\Omega$ (Typ.)@ $V_{GS} = 10V$, $I_D = 3.25A$
- Low gate charge (Typ. 13nC)
- Low C_{rss} (Typ. 7pF)
- · Fast switching
- · 100% avalanche tested
- · Improved dv/dt capability
- · ESD Improved capability
- · RoHS compliant

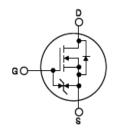
Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DOMS technology.

This advance technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutationmode. These devices are well suited for high efficient switched mode power supplies and active power factor correction.







MOSFET Maximum Ratings T_C = 25°C unless otherwise noted*

Symbol		Parameter		FDP7N60NZ	FDPF7N60NZ	Units
V _{DSS}	Drain to Source Voltage			60	V	
V _{GSS}	Gate to Source Voltage	Sate to Source Voltage			30	V
	Drain Current	-Continuous (T _C = 25°C)		6.5	6.5*	Α
I _D	Dialii Current	-Continuous (T _C = 100°C)		3.9	3.9*	A
I _{DM}	Drain Current - Pulsed (Note 1)) 26 26*		Α	
E _{AS}	Single Pulsed Avalanche Energy		(Note 2)	275		mJ
I _{AR}	Avalanche Current		(Note 1)	6.5		Α
E _{AR}	Repetitive Avalanche Energy		(Note 1)	14.7		mJ
dv/dt	Peak Diode Recovery dv/dt		(Note 3)	10		V/ns
В	Dower Dissipation	$(T_C = 25^{\circ}C)$		147	33	W
P_{D}	Power Dissipation - Derate above 25°C		1.2	0.26	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150		°С	
T _L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds			30	00	°C

^{*}Drain current limited by maximum junction temperature

Thermal Characteristics

Symbol	Parameter	FDP7N60NZ	FDPF7N60NZ	Units
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.85	3.8	
$R_{\theta CS}$	Thermal Resistance, Case to Sink Typ. 0.5		-	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	62.5	62.5	

查询"FDP7N60NZ"供应商 Package Marking and Ordering Information $T_C = 25$ °C unless otherwise noted

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDP7N60NZ	FDP7N60NZ	TO-220	-	-	50
FDPF7N60NZ	FDPF7N60NZ	TO-220F	-	=	50

Electrical Characteristics

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Charac	eteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A$, $V_{GS} = 0 V$, $T_J = 25 ^{\circ} C$	600	-	-	V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I _D = 250μA, Referenced to 25°C	-	0.6	-	V/°C
	Zero Gate Voltage Drain Current	$V_{DS} = 600V, V_{GS} = 0V$	-	-	1	
IDSS	Zero Gate voltage Drain Current	$V_{DS} = 480V, T_{C} = 125^{\circ}C$	-	-	10	μΑ
I _{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 25V, V_{DS} = 0V$	-	-	±10	μΑ

On Characteristics

V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	3	-	5	V
R _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 10V, I_D = 3.25A$	-	1.05	1.25	Ω
9 _{FS}	Forward Transconductance	$V_{DS} = 20V, I_D = 3.25A$ (Note 4)	-	7.3	-	S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 05V V 0V		=	550	730	pF
C _{oss}	Output Capacitance	$V_{DS} = 25V, V_{GS} = 0V$ f = 1MHz		-	70	90	pF
C _{rss}	Reverse Transfer Capacitance	1 – 1101112		-	7	10	pF
$Q_{g(tot)}$	Total Gate Charge at 10V			-	13	17	nC
Q_{gs}	Gate to Source Gate Charge	$V_{DS} = 480V, I_{D} = 6.5A$		-	3	-	nC
Q _{gd}	Gate to Drain "Miller" Charge	V _{GS} = 10V	(Note 4, 5)	=	5.6	-	nC

Switching Characteristics

t _{d(on)}	Turn-On Delay Time			-	17.5	45	ns
t _r	Turn-On Rise Time	$V_{DD} = 300V, I_D = 6.5A$		-	30	70	ns
t _{d(off)}	Turn-Off Delay Time	$R_G = 25\Omega$		-	40	90	ns
t _f	Turn-Off Fall Time	(Note	4, 5)	-	25	60	ns

Drain-Source Diode Characteristics

I_S	Maximum Continuous Drain to Source Diode Forward Current			-	-	6.5	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current			-	-	26	Α
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0V, I_{SD} = 6.5A$		-	-	1.4	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0V, I_{SD} = 6.5A$		-	250	-	ns
Q _{rr}	Reverse Recovery Charge	$dI_F/dt = 100A/\mu s$	(Note 4)	-	1.4	-	μС

- **Notes:**1. Repetitive Rating: Pulse width limited by maximum junction temperature 2: L =13mH, I_{AS} = 6.5A, V_{DD} = 50V, R_{G} = 250, Starting T_{J} = 25°C 3: I_{SD} ≤ 6.5A, di/dt ≤ 200A/µs, V_{DD} ≤ BV $_{DSS}$, Starting T_{J} = 25°C 4: Pulse Test: Pulse width ≤ 300 μ s, Duty Cycle ≤ 2% 5: Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

Figure 1. On-Region Characteristics

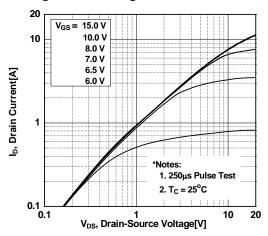


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

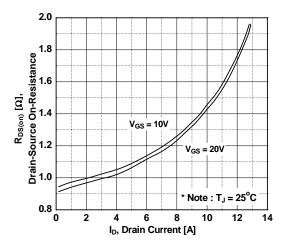


Figure 5. Capacitance Characteristics

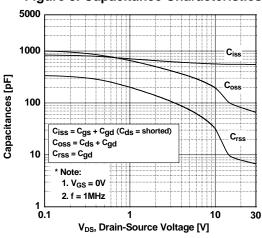


Figure 2. Transfer Characteristics

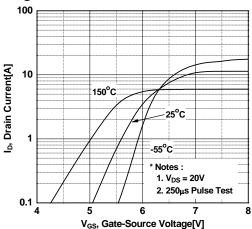


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

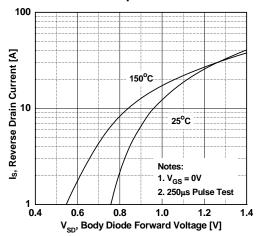
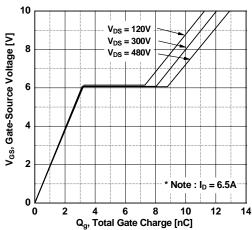


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

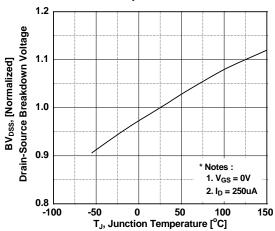


Figure 8. On-Resistance Variation vs Temperature

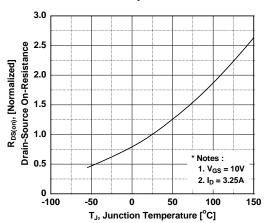


Figure 9. Maximum Safe Operating Area -FDPF7N60NZ

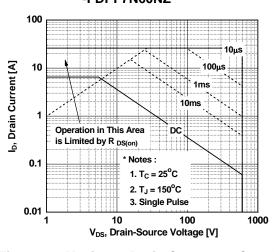


Figure 10. Maximum Drain Current -FDP7N60NZ

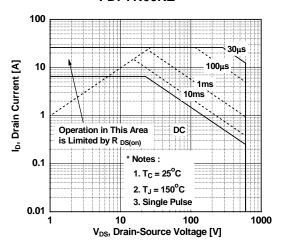


Figure 11. Maximum Drain Current vs Case Temperature

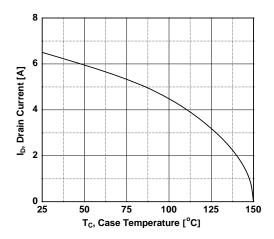


Figure 12. Transient Thermal Response Curve -FDPF7N60NZ

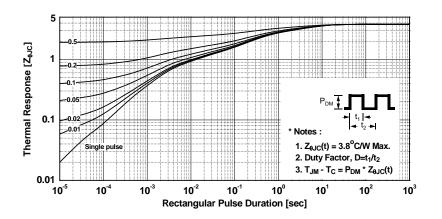
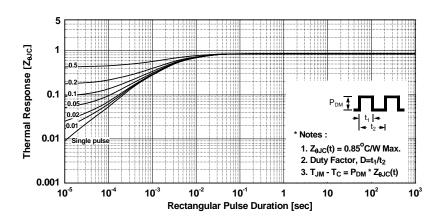
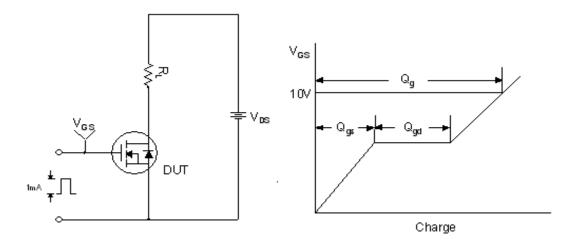


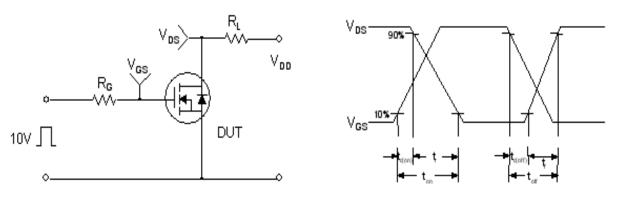
Figure 13. Transient Thermal Response Curve -FDP7N60NZ



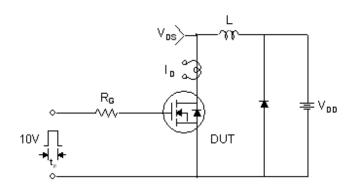
Gate Charge Test Circuit & Waveform

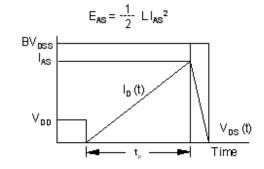


Resistive Switching Test Circuit & Waveforms

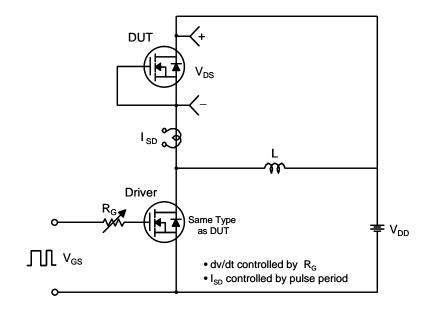


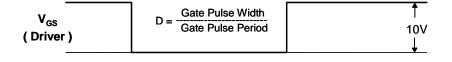
Unclamped Inductive Switching Test Circuit & Waveforms

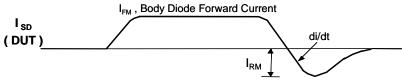




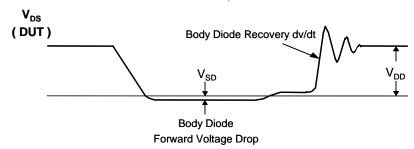
Peak Diode Recovery dv/dt Test Circuit & Waveforms





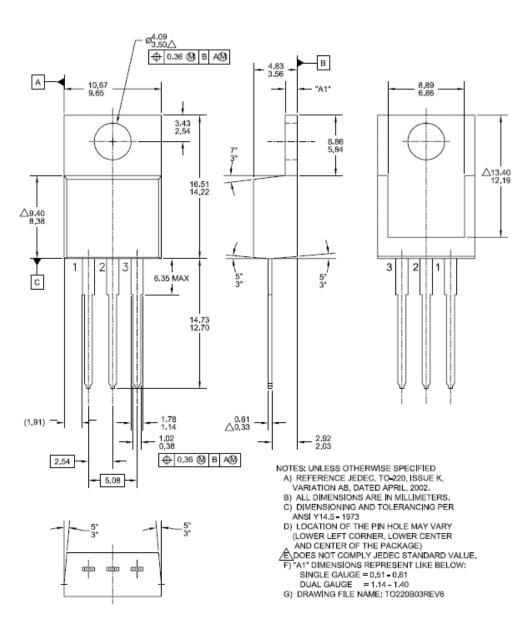


Body Diode Reverse Current



查询"FDP7N60NZ"供应商 Mechanical Dimensions

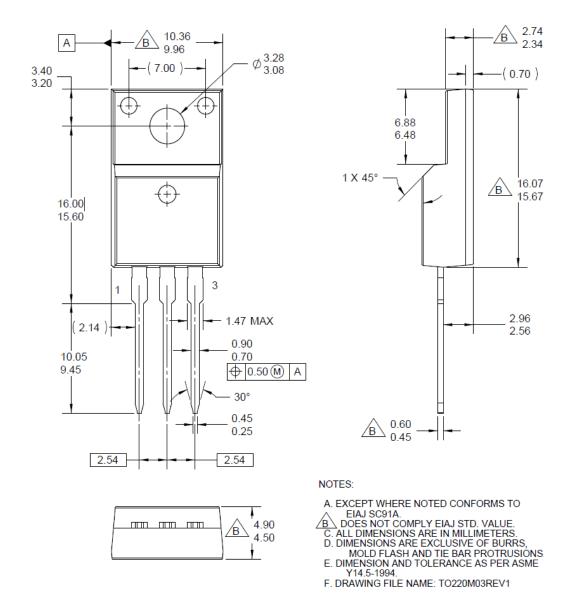
TO-220



Dimensions in Millimeters

Package Dimensions (Continued)

TO-220F



* Front/Back Side Isolation Voltage: 2500V

Dimensions in Millimeters



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